

TITLE OF INVENTION

SOLDER ALLOY, SOLDER BALL AND SOLDER JOINT

ABSTRACT

The present invention employs a lead-free and antimony-free solder alloy which has an alloy composition that contains from 1.0% by mass to 4.0% by mass of Ag, from 0.1% by mass to 1.0% by mass of Cu, from 0.1% by mass to 9.0% by mass of Bi, from 0.005% by mass to 0.3% by mass of Ni and from 0.001% by mass to 0.015% by mass of Ge, with the balance being made up of Sn.

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